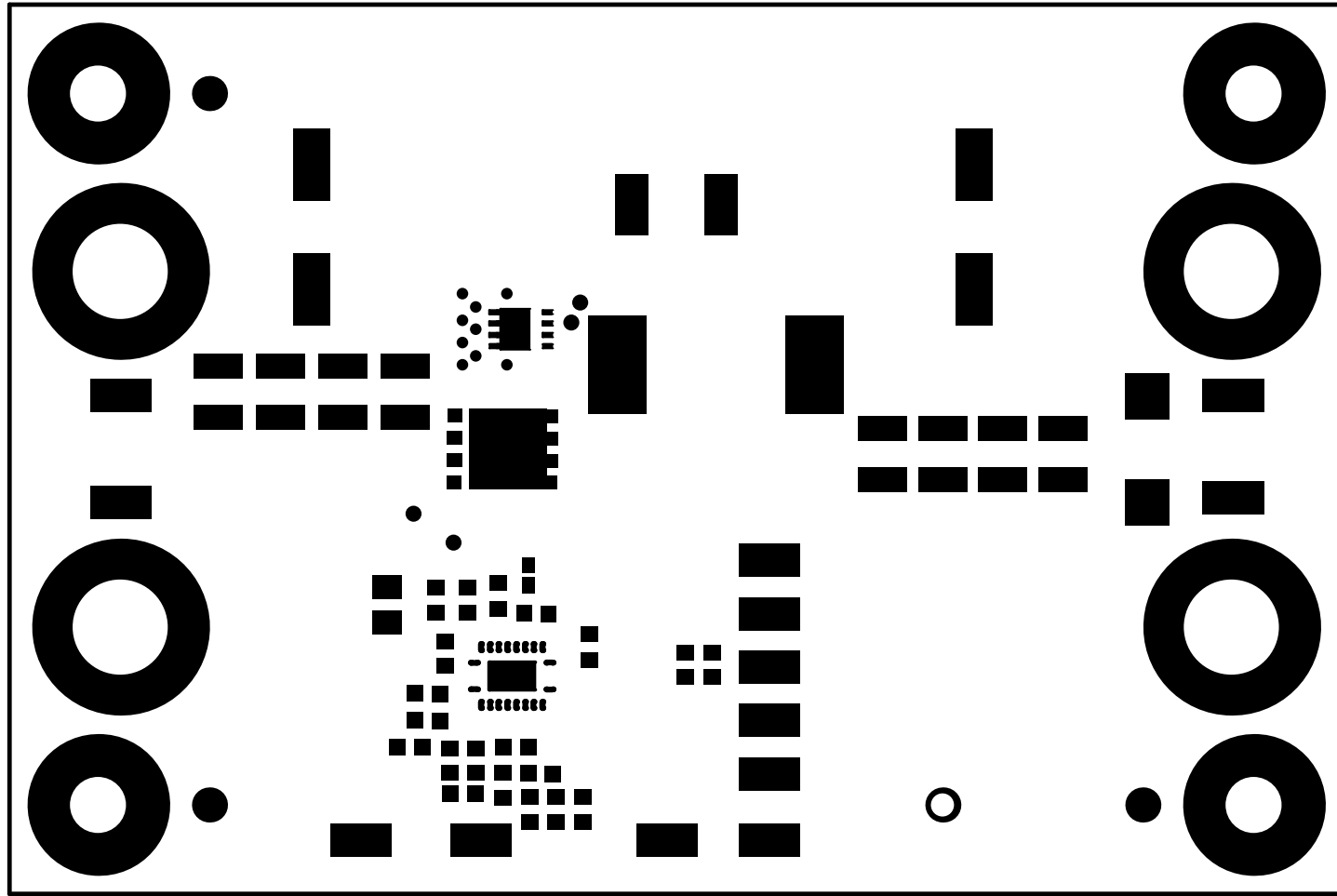
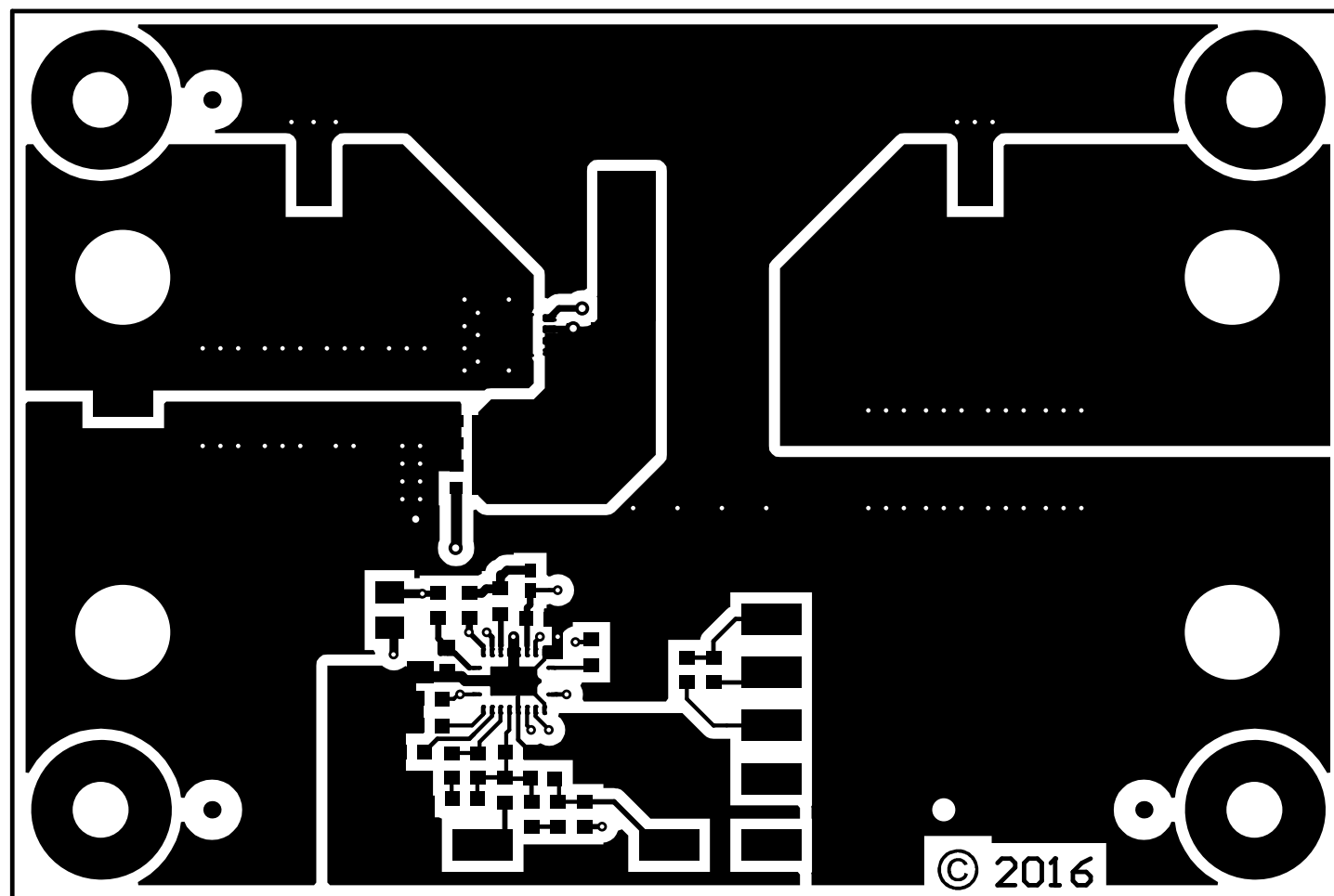


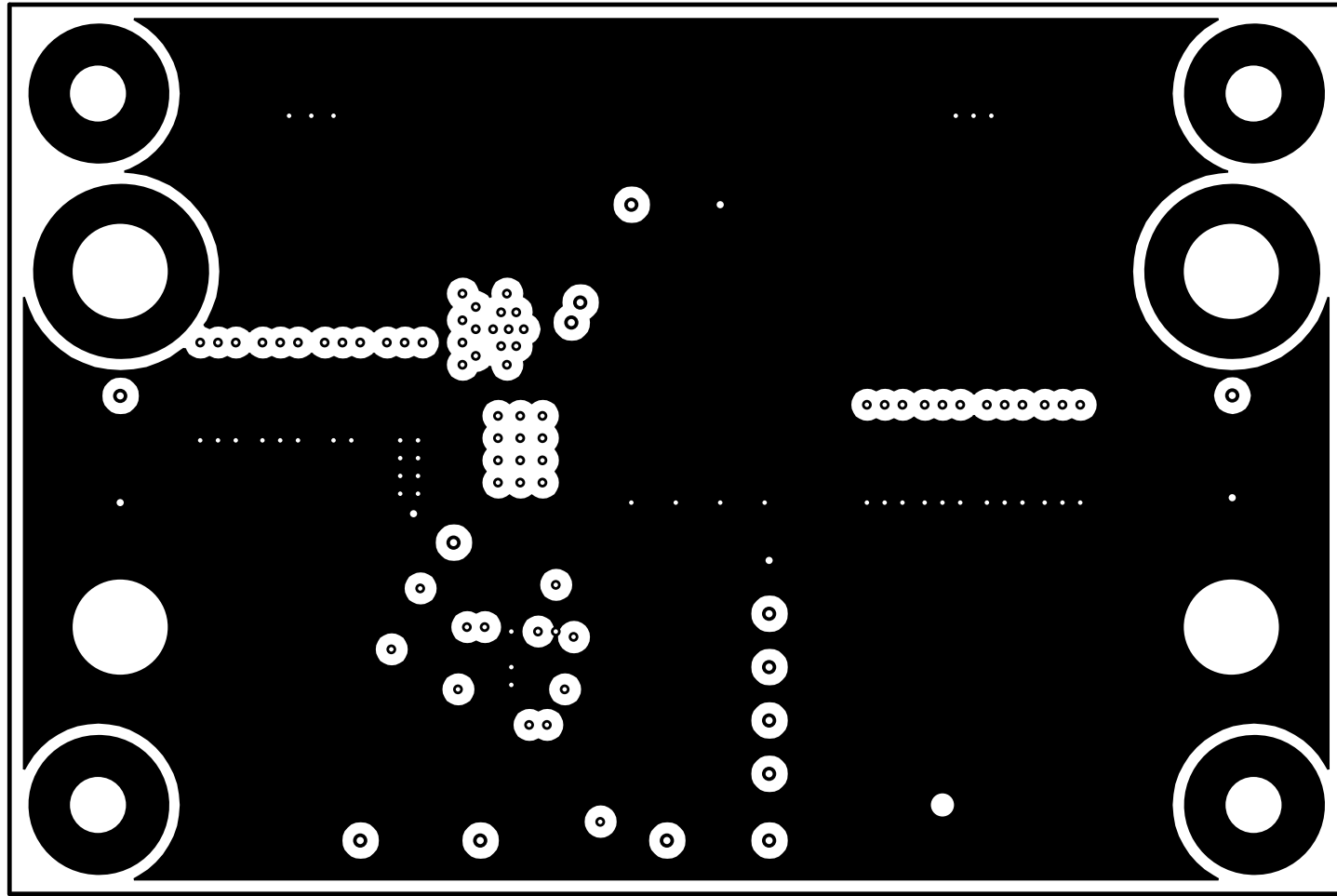
| | | | |
|----------------------------------|-----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP20178 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay | TID #: PMP20178 | | |
| PLOT NAME = Top Overlay | GENERATED : 5/14/2016 | 3:44:46 PM | TEXAS INSTRUMENTS |



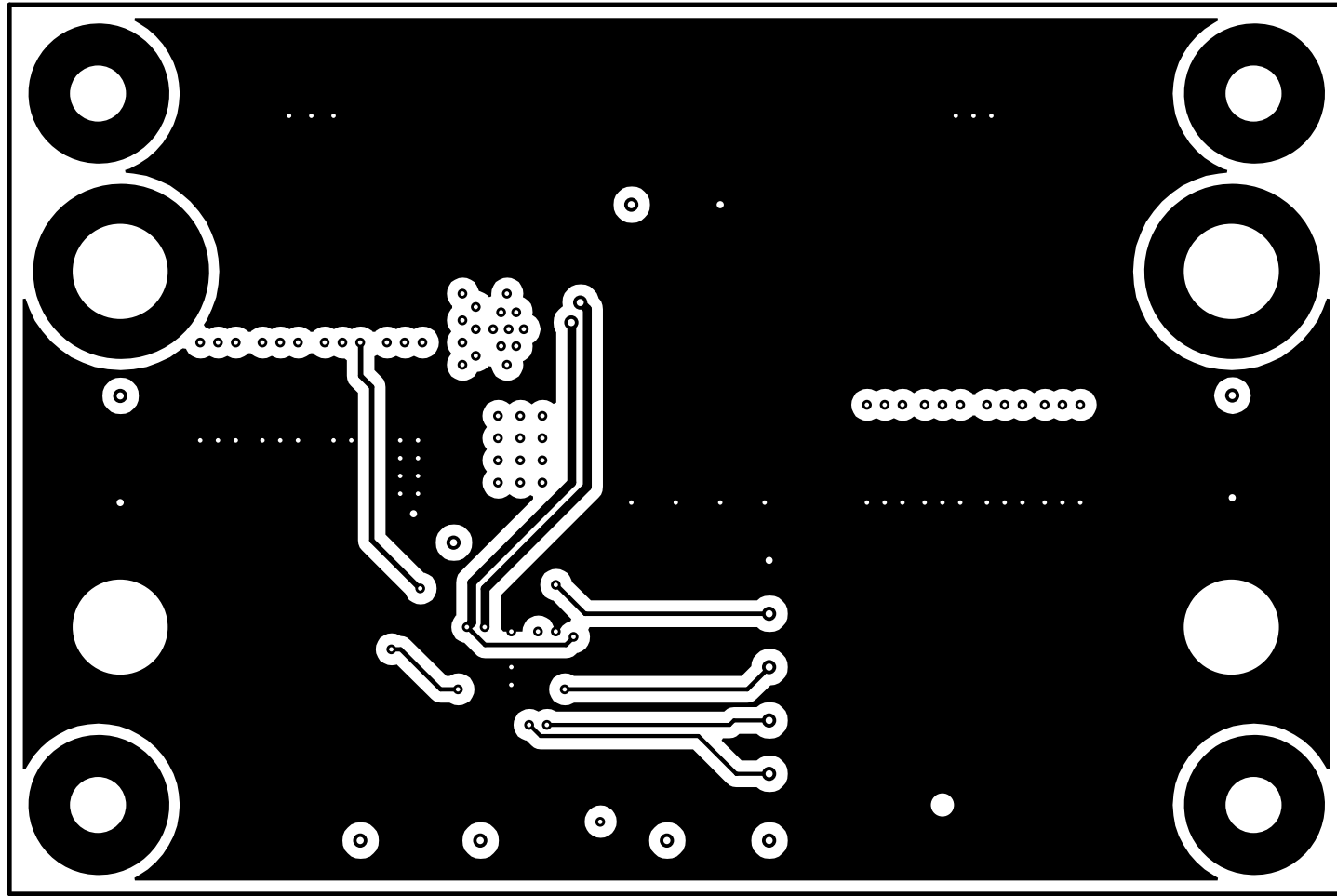
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|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP20178 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder | TID #: PMP20178 | | |
| PLOT NAME = Top Solder Mask | GENERATED : 5/14/2016 3:44:46 PM | TEXAS INSTRUMENTS | |



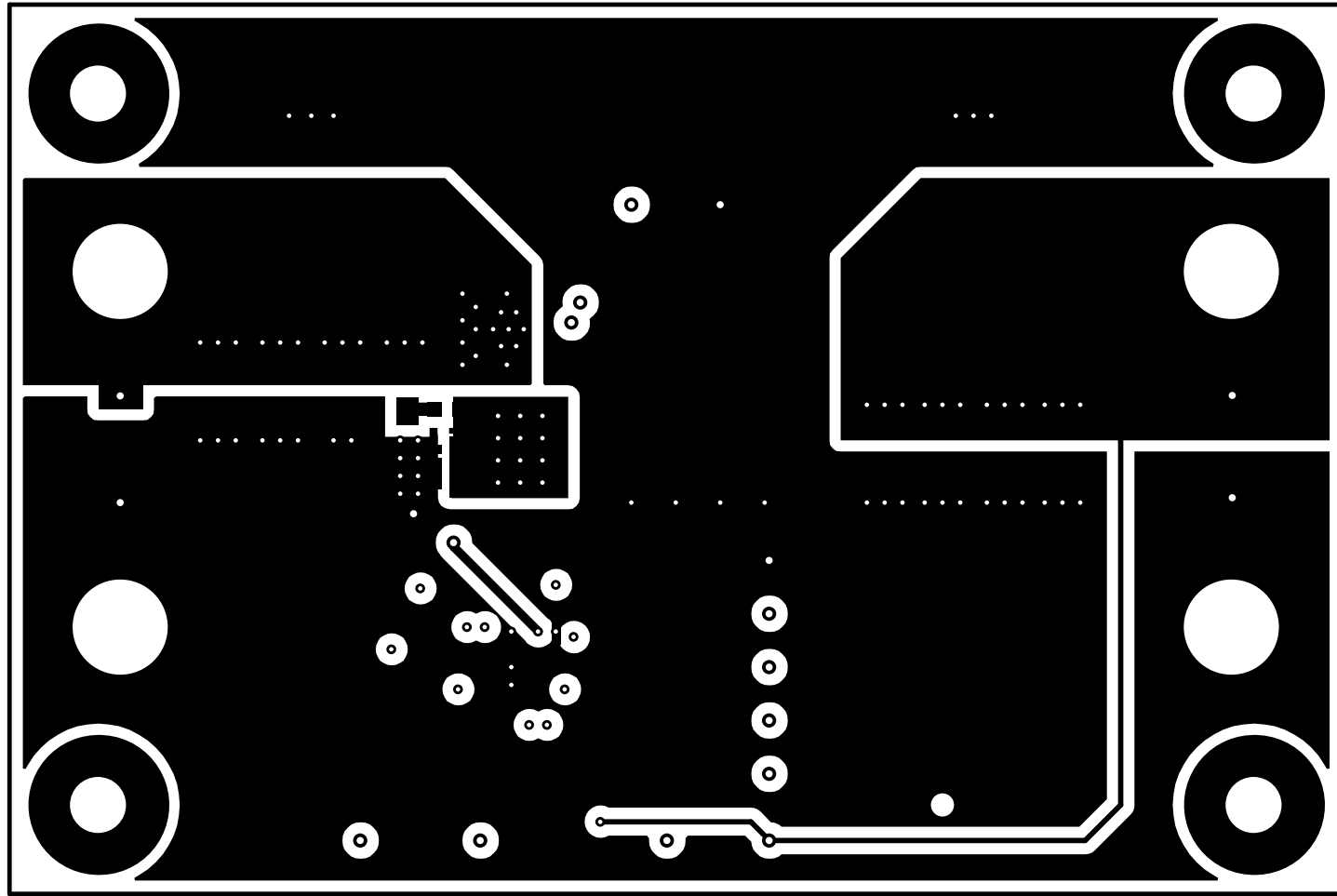
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|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP20178 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer | TID #: PMP20178 | | |
| PLOT NAME = Top Layer | GENERATED : 5/14/2016 3:44:47 PM | TEXAS INSTRUMENTS | |



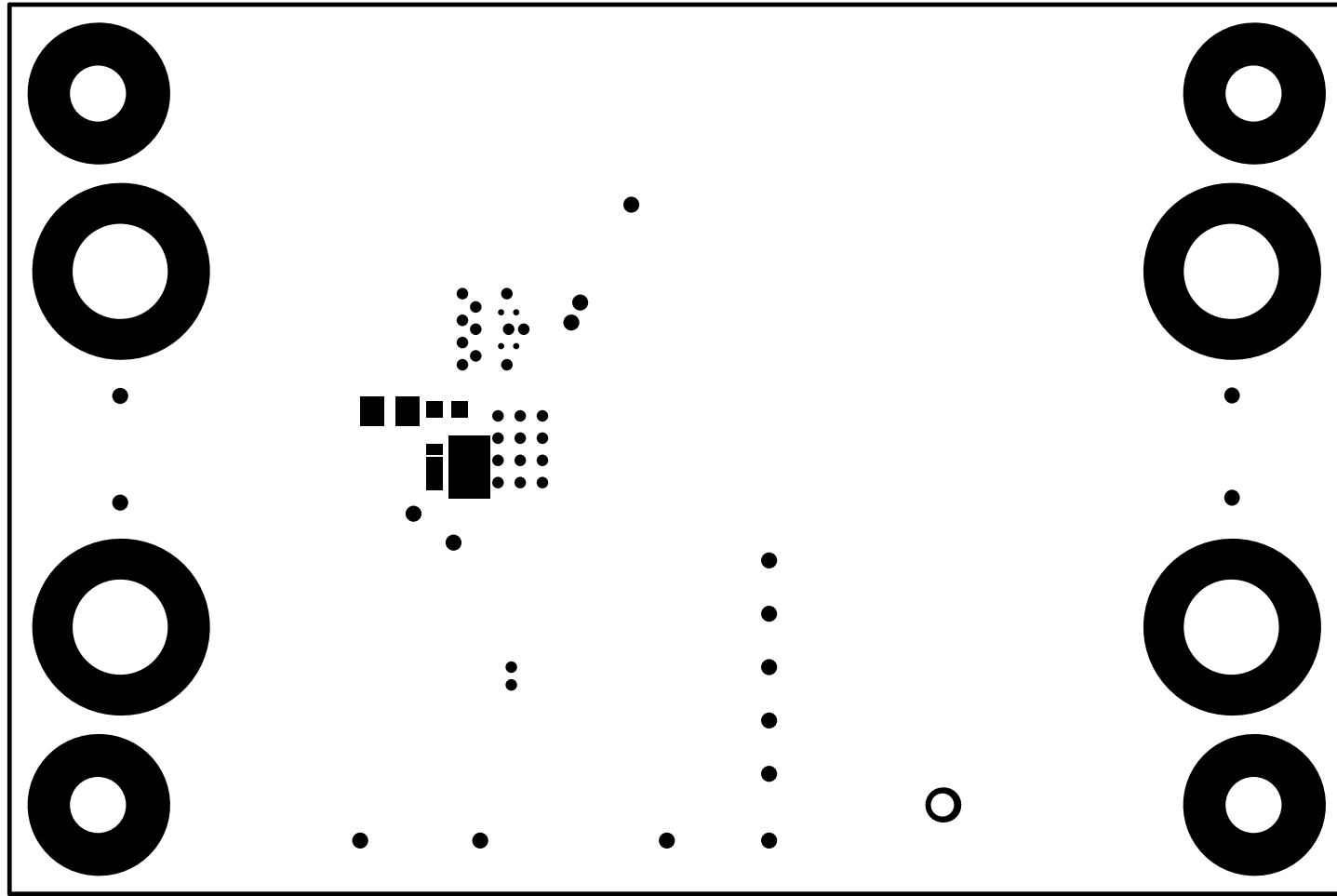
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP20178 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = | TID #: PMP20178 | | |
| PLOT NAME = Signal Layer 1 | GENERATED : 5/14/2016 3:44:47 PM | TEXAS INSTRUMENTS | |



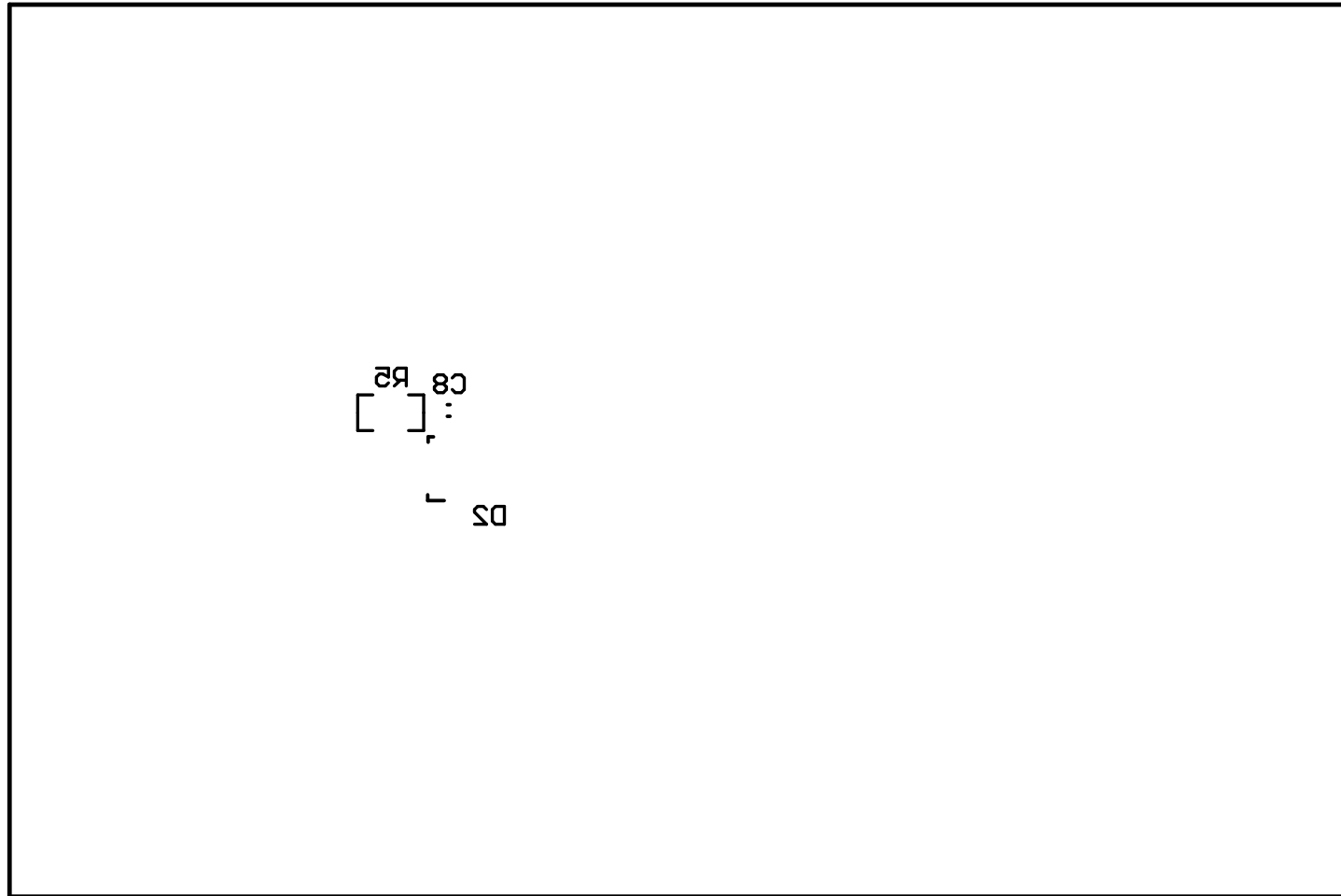
| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP20178 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = | TID #: PMP20178 | | |
| PLOT NAME = Signal Layer 2 | GENERATED : 5/14/2016 3:44:48 PM | TEXAS INSTRUMENTS | |



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|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP20178 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer | TID #: PMP20178 | | |
| PLOT NAME = Bottom Layer | GENERATED : 5/14/2016 3:44:48 PM | TEXAS INSTRUMENTS | |

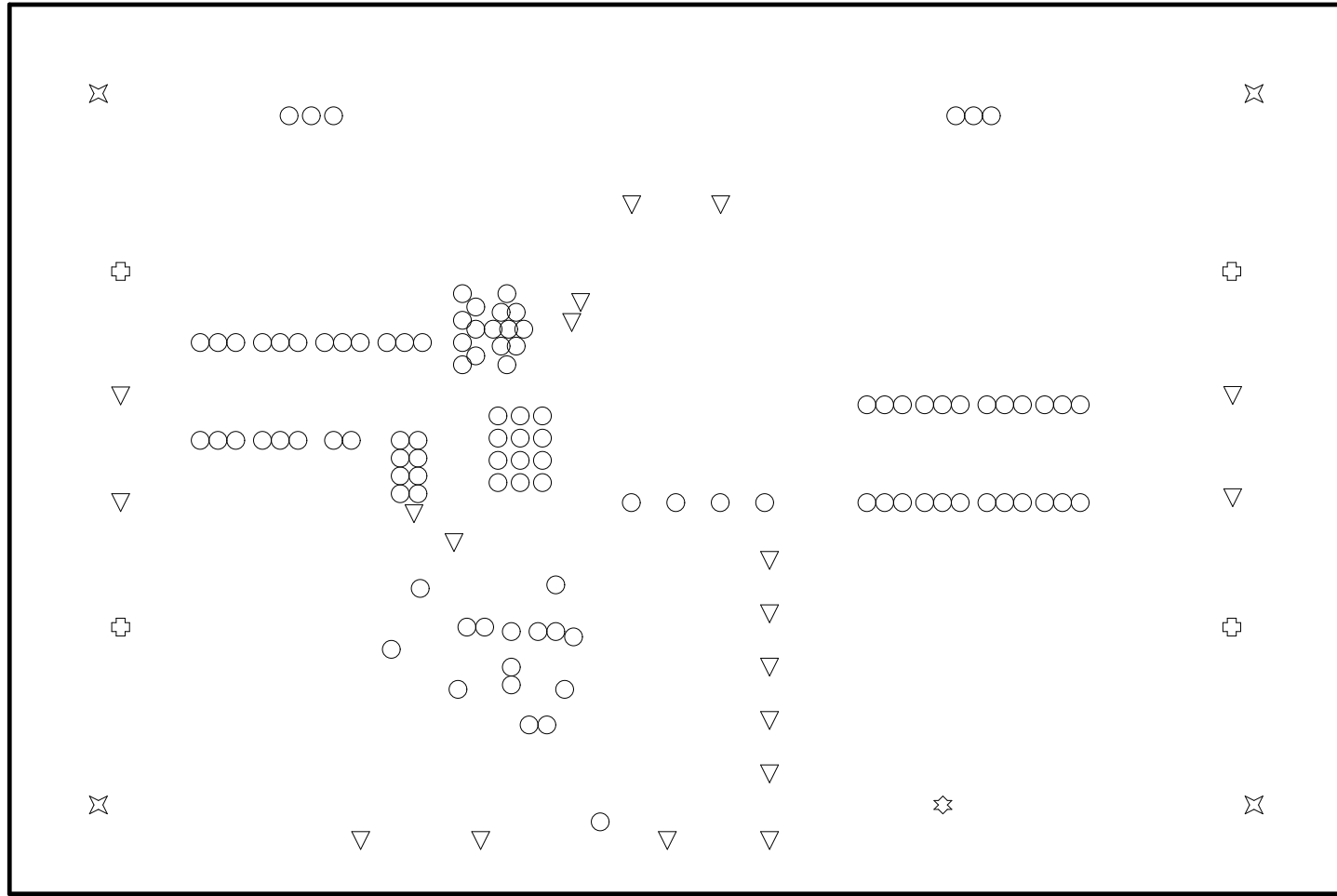


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|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP20178 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = Bottom Solder | TID #: PMP20178 | | |
| PLOT NAME = Bottom Solder Mask | GENERATED : 5/14/2016 3:44:49 PM | TEXAS INSTRUMENTS | |

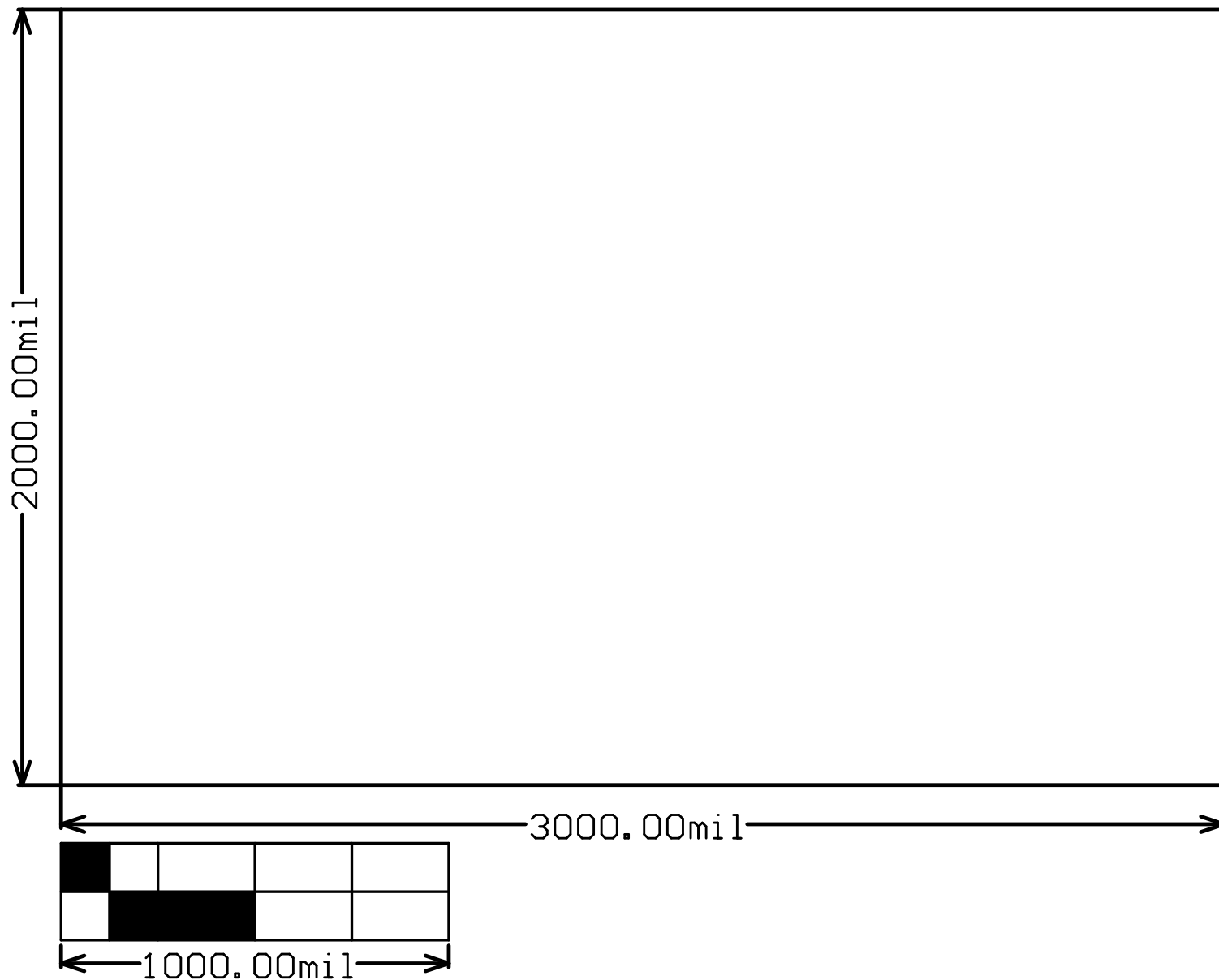


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| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP20178 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay | TID #: PMP20178 | | |
| PLOT NAME = Bottom Overlay | GENERATED : 5/14/2016 3:44:49 PM | TEXAS INSTRUMENTS | |



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|----------------------------------|-----------------------|------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP20178 | REV: A | SVN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing | TID #: PMP20178 | | |
| PLOT NAME = Drill Drawing | GENERATED : 5/14/2016 | 3:44:49 PM | TEXAS INSTRUMENTS |



| | | | |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP20178 | REV: A | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions | TID #: PMP20178 | | |
| PLOT NAME = Board Dimensions | GENERATED : 5/14/2016 3:44:50 PM | TEXAS INSTRUMENTS | |

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